

# FDMA1025P

## Dual P-Channel PowerTrench® MOSFET

-20V, -3.1A, 105mΩ

### Features

- Max  $r_{DS(on)}$  = 155mΩ at  $V_{GS} = -4.5V$ ,  $I_D = -3.1A$
- Max  $r_{DS(on)}$  = 220mΩ at  $V_{GS} = -2.5V$ ,  $I_D = -2.3A$
- Low profile - 0.8mm maximum - in the new package MicroFET 2X2
- RoHS Compliant



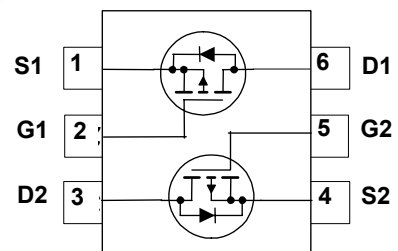
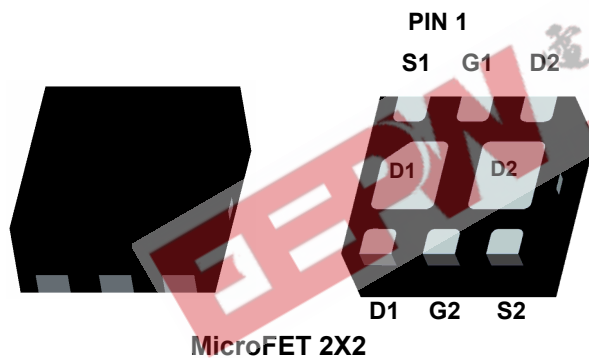
### General Description

This device is designed specifically as a single package solution for the battery charge switch in cellular handset and other ultra-portable applications. It features two independent P-Channel MOSFETs with low on-state resistance for minimum conduction losses. When connected in the typical common source configuration, bi-directional current flow is possible.

The MicroFET 2X2 package offers exceptional thermal performance for its physical size and well suited to linear mode applications.

### Application

- DC - DC Conversion



### MOSFET Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	-20	V
$V_{GS}$	Gate to Source Voltage	±12	V
$I_D$	Drain Current -Continuous	(Note 1a) -3.1	A
	-Pulsed	-6	
$P_D$	Power Dissipation for Single Operation	(Note 1a) 1.4	W
	Power Dissipation	(Note 1b) 0.7	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

### Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance Single Operation, Junction to Ambient	(Note 1a) 86	°C/W
$R_{\theta JA}$	Thermal Resistance Single Operation, Junction to Ambient	(Note 1b) 173	
$R_{\theta JA}$	Thermal Resistance Dual Operation, Junction to Ambient	69	
$R_{\theta JA}$	Thermal Resistance Dual Operation, Junction to Ambient	151	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
025	FDMA1025P	MLP2X2	7"	8mm	3000 units

### Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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#### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$ , referenced to $25^\circ\text{C}$		14		$\text{mV}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -16\text{V}, V_{GS} = 0\text{V}$ $T_J = 125^\circ\text{C}$			-1 -100	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	nA

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.4	-0.9	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$ , referenced to $25^\circ\text{C}$		-3.8		$\text{mV}/^\circ\text{C}$
$r_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = -4.5\text{V}, I_D = -3.1\text{A}$ $V_{GS} = -2.5\text{V}, I_D = -2.3\text{A}$ $V_{GS} = -4.5\text{V}, I_D = -3.1\text{A}, T_J = 125^\circ\text{C}$		88 144 121	155 220 220	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = -5\text{V}, I_D = -3.1\text{A}$		6.2		S

#### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = -10\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		340	450	pF
$C_{oss}$	Output Capacitance			80	105	pF
$C_{rss}$	Reverse Transfer Capacitance			45	70	pF

#### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -10\text{V}, I_D = -3.1\text{A}$ $V_{GS} = -4.5\text{V}, R_{GEN} = 6\Omega$		5	10	ns
$t_r$	Rise Time			14	26	ns
$t_{d(off)}$	Turn-Off Delay Time			13	24	ns
$t_f$	Fall Time			8	16	ns
$Q_g(TOT)$	Total Gate Charge at 4.5V		$V_{GS} = 0\text{V to } -4.5\text{V}$ $V_{DD} = -10\text{V}$ $I_D = -3.1\text{A}$		3.4	4.8
$Q_{gs}$	Gate to Source Gate Charge			0.8		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			1.0		nC

#### Drain-Source Diode Characteristics

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -1.1\text{A}$ (Note 2)		-0.8	-1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F = -3.1\text{A}, di/dt = 100\text{A}/\mu\text{s}$		17	26	ns
$Q_{rr}$	Reverse Recovery Charge			10	15	nC

#### Notes:

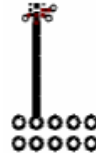
1:  $R_{\theta JA}$  is determined with the device mounted on a  $1\text{ in}^2$  oz copper pad on a  $1.5 \times 1.5\text{ in.}$  board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.

(a)  $R_{\theta JA} = 86^\circ\text{C}/\text{W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper,  $1.5 \times 1.5 \times 0.062\text{ in.}$  thick PCB.

(b)  $R_{\theta JA} = 173^\circ\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper.



a.  $86^\circ\text{C}/\text{W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper.



b.  $173^\circ\text{C}/\text{W}$  when mounted on a minimum pad.

2: Pulse Test: Pulse Width <  $300\mu\text{s}$ , Duty cycle < 2.0%.

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

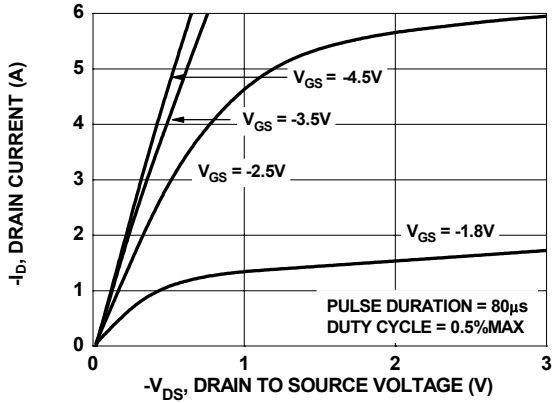


Figure 1. On Region Characteristics

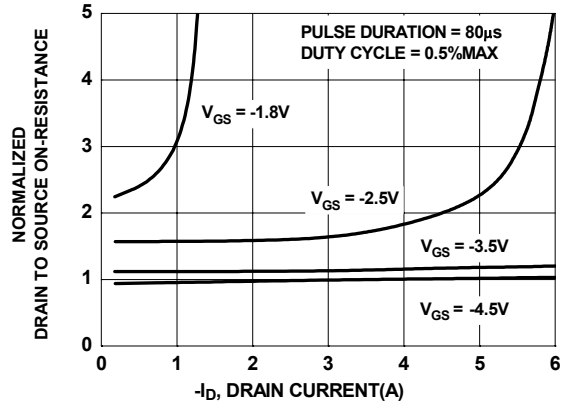


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

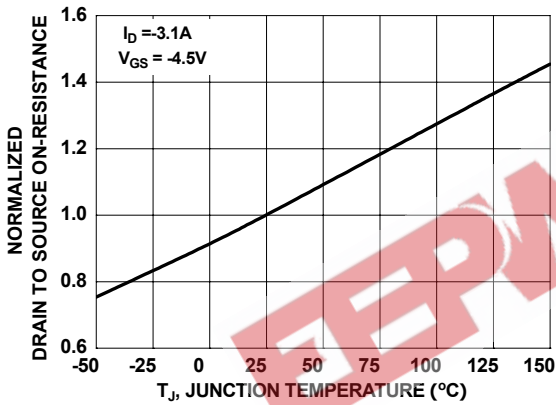


Figure 3. Normalized On Resistance vs Junction Temperature

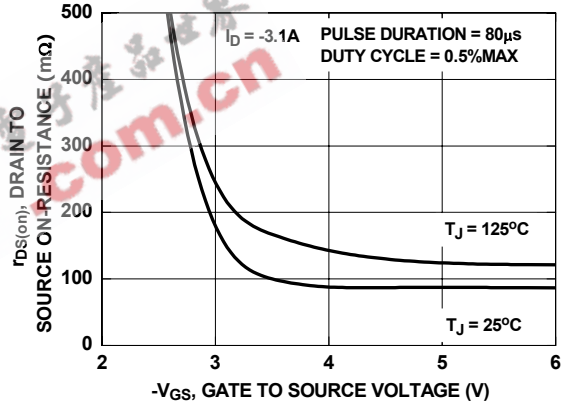


Figure 4. On-Resistance vs Gate to Source Voltage

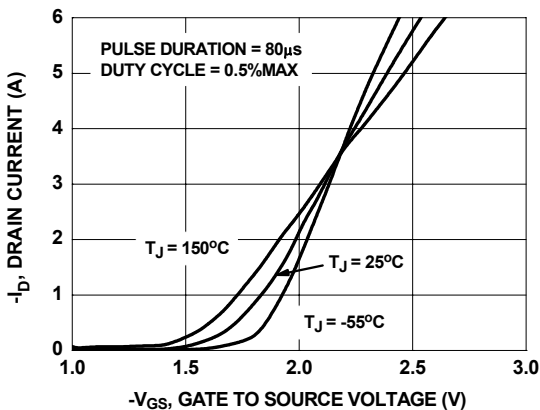


Figure 5. Transfer Characteristics

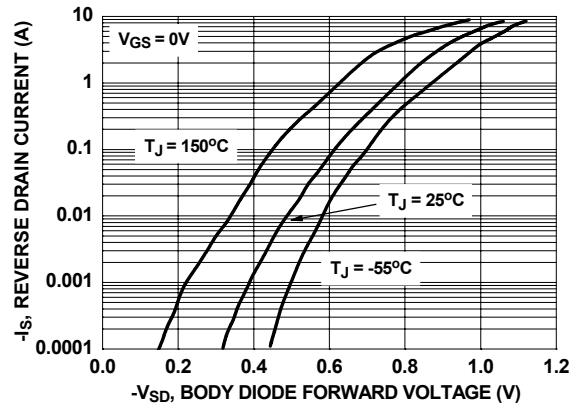
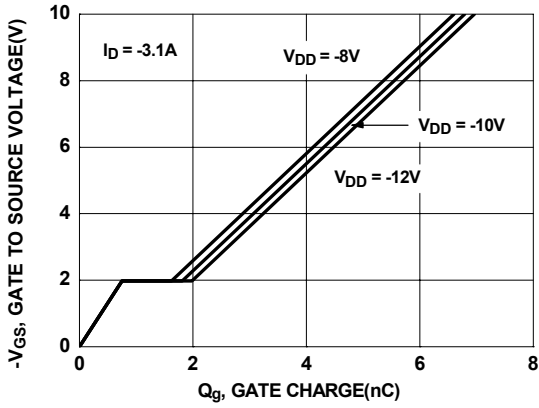
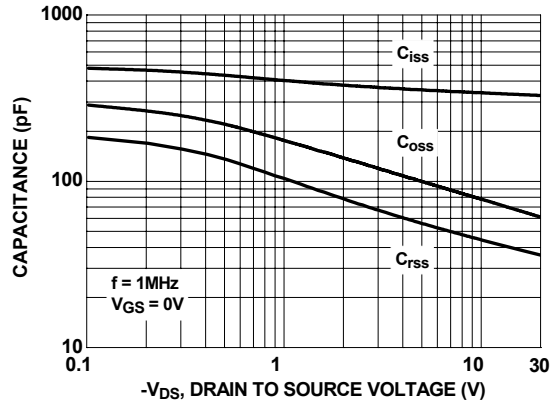


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

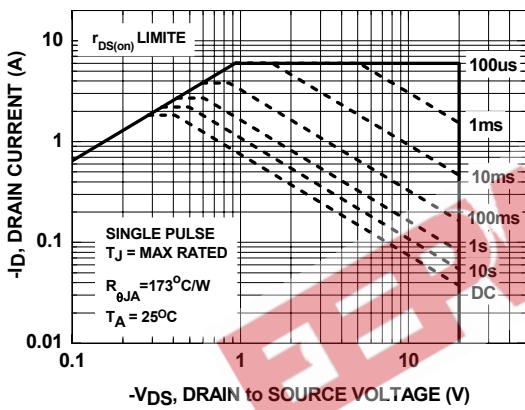
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



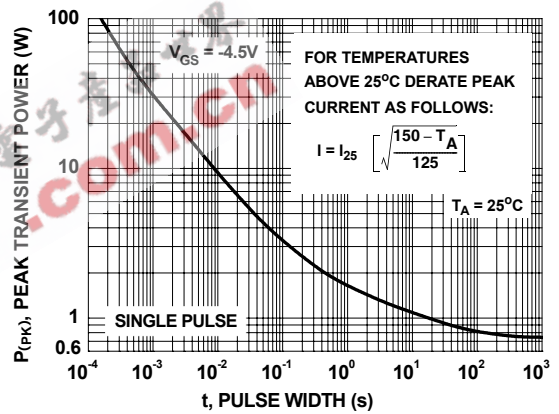
**Figure 7. Gate Charge Characteristics**



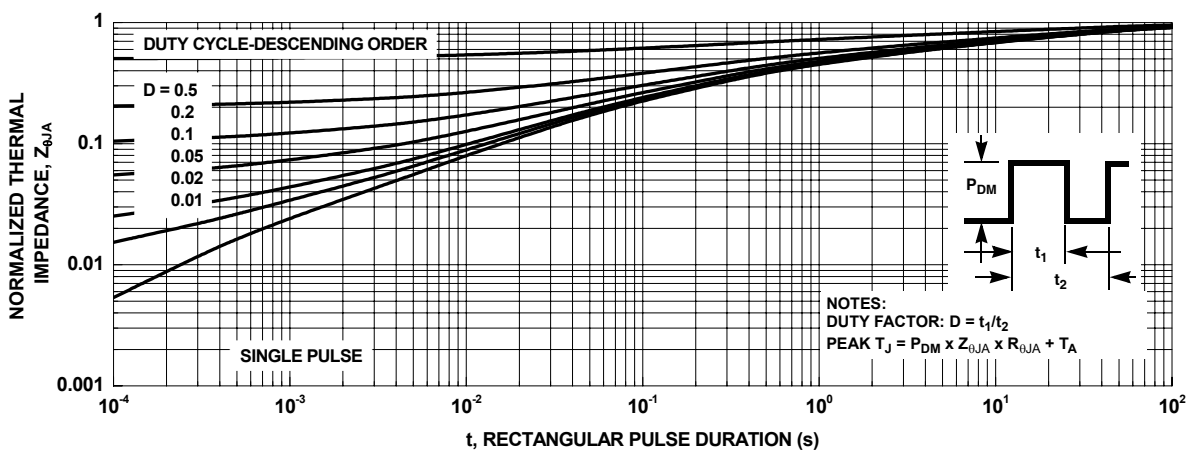
**Figure 8. Capacitance vs Drain to Source Voltage**



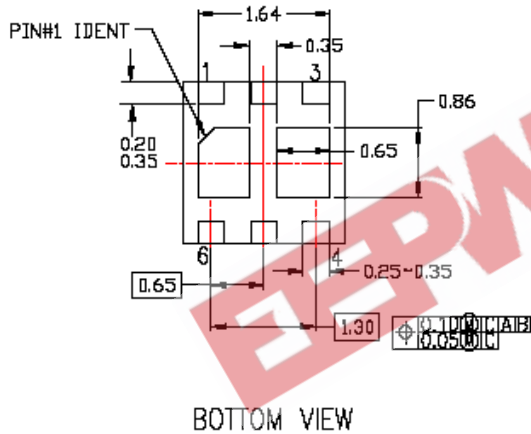
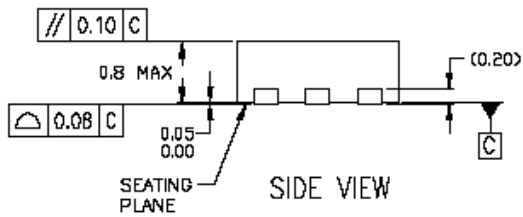
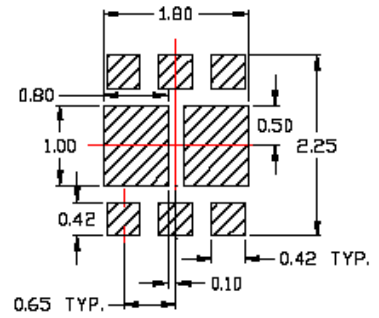
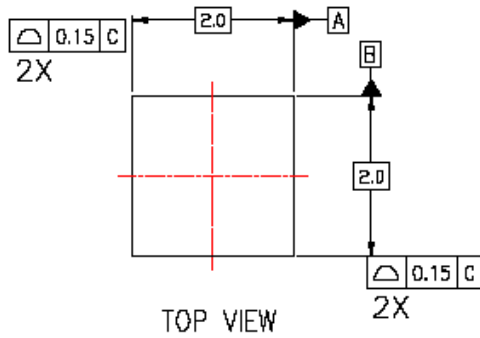
**Figure 9. Forward Bias Safe Operating Area**



**Figure 10. Single Pulse Maximum Power Dissipation**



**Figure 11. Transient Thermal Response Curve**



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VCCC, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

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